

SEMICONDUCTOR PACKAGE AND METHOD FOR MANUFACTURING THE SAME

Abstract

A semiconductor package positioned on a first substrate includes a second substrate having a first surface and a second surface, a chip positioned on the first surface of the second substrate, a plurality of first bonding balls positioned on the second surface of the second substrate and arranged in a line along a first direction for connecting the second substrate to the first substrate, and at least a dummy bonding bar positioned on the second surface of the second substrate for connecting the second substrate to the first substrate and preventing the semiconductor package from inclining to one side.